## BERITA ONLINE NEW STRAITS TIMES

**TARIKH: 30 OKTOBER 2022 (AHAD)** 



## AT&S Malaysia, MIMOS in IC substrate R&D pact

By NST Business - October 30, 2022 @ 2:15pm



The partnership was officiated following the signing of a Memorandum of Understanding (MoU) earlier this month, which was witnessed by Prime Minister Datuk Seri Ismail Sabri Yaakob.

KUALA LUMPUR: AT&S Austria Technologie & Systemtechnik (Malaysia) Sdn Bhd (AT&S Malaysia) ) has partnered with MIMOS Bhd for joint research and development (R&D) activities.

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"With the signing and exchange of MOU with MIMOS, AT&S Malaysia is honoured and looks forward to contribute to the microelectronics and technology fields in Malaysia.

"Specifically, AT&S Malaysia and MIMOS seek to carry out joint IC substrate research and development activities that would potentially engage the Ministry of Science, Technology and Innovation (MOSTI) and Ministry of Higher Education (MOHE)," the company said in a statement today.

AT&S Malaysia said in addition, both parties had expressed interest to cooperate in technology assessment and development in the area of advanced packaging in order to strengthen the local industry capabilities, together with a focus to help develop critical talents in advanced packaging through MOSTI Deeptech and Futureskills initiative.

Potentially, the establishment of an institute with a selected University in Malaysia is considered in the joint pursuit for the purpose of talent development.

AT&S managing director Vittorio Villari said the rapid emergence and application of artificial intelligence, Internet of Things and Big Data had created a radical shift in global demand for microelectronics products such as the company's high-end IC substrates.

"They are widely used in high-performance computers, server, cloud, edge computing and many more. As such, we believe that our know-how and presence here would help to raise the global competitiveness of Malaysia in IC substrates field.

"Now, through the cooperation with MIMOS, we hope to further accelerate the advancement of technology solutions to benefit the societies' greatest needs," he said.

MIMOS president and chief executive officer Dr Iskandar Samad said the collaboration supported the nation's renewed aspiration for a more technologically driven future for the domestic E&E sector.

"Malaysia needs more higher value-added activities to strengthen its domestic ecosystem, and targeted collaborations with leading global players like AT&S who have established strength in IC substrates and advanced packaging will be key to unlock new opportunities for the country, be it in developing local industry or producing more high-skilled talent. "This initiative also reinforces our new branding, MIMOS Global, that underscores a more international approach to partnerships and technology co-development with established market players," he said.